

ABSTRACT OF THE DISCLOSURE

Provide a discrete semiconductor device, particularly  
a discrete semiconductor device for small signal operation with  
a smaller packaging area and has excellent high frequency  
5 characteristics and good heat dissipation performance, and a  
method for producing the same. The discrete semiconductor  
elements are mounted on die bond pads and wire bond pads with  
the packaging surface being sealed with a resin, and connecting  
the back faces of the die bond pads and the wire bond pads  
10 directly to a mother board.

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